



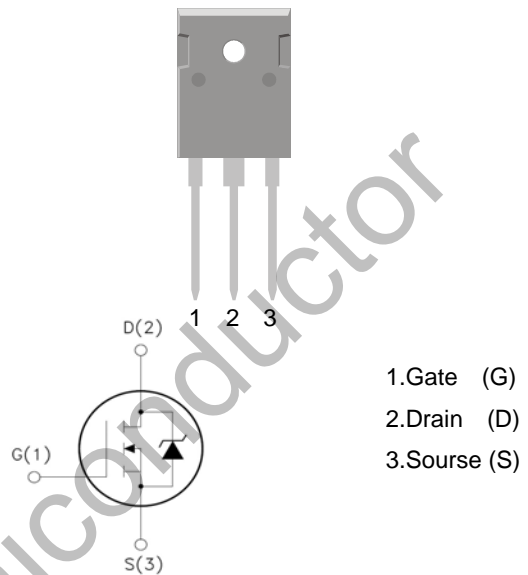
## WGA65R099G

650V N-Channel MOSFET

### Features:

- Low Intrinsic Capacitances.
- Excellent Switching Characteristics.
- Extended Safe Operating Area.
- Unrivalled Gate Charge :Qg=77 nC (Typ.).
- V<sub>DSS</sub>=650V, I<sub>D</sub>= 33 A
- R<sub>DS(on)</sub> :0.115Ω (Max) @V<sub>G</sub>=10V
- 100% Avalanche Tested

TO-247



### Absolute Maximum Rating (T<sub>c</sub>=25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit	Note
Drain – Source voltage	V <sub>DSS</sub>	600	V	
Gate – Source voltage	V <sub>GSS</sub>	±30	V	
Continuous drain current	I <sub>D</sub>	33	A	T <sub>c</sub> =25°C
		20.9	A	T <sub>c</sub> =100°C
Pulsed drain current <sup>(1)</sup>	I <sub>DM</sub>	99	A	
Power dissipation	P <sub>D</sub>	255	W	
Single - pulse avalanche energy	E <sub>AS</sub>	700	mJ	
MOSFET dv/dt ruggedness	dv/dt	50	V/ns	
Diode dv/dt ruggedness	dv/dt	15	V/ns	
Storage temperature	T <sub>stg</sub>	-55 ~150	°C	
Maximum operating junction temperature	T <sub>j</sub>	150	°C	

1) Pulse width t<sub>p</sub> limited by T<sub>j,max</sub>

2) I<sub>SD</sub> ≤ I<sub>D</sub>, V<sub>DS peak</sub> ≤ V<sub>(BR)DSS</sub>

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case max	$R_{thjc}$	0.49	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction-ambient max	$R_{thja}$	62.5	$^{\circ}\text{C}/\text{W}$

**Static Characteristics ( $T_c=25^{\circ}\text{C}$  unless otherwise specified)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Drain – Source Breakdown voltage	$V_{(BR)DSS}$	600	-	-	V	$V_{GS} = 0\text{V}, I_D=0.25\text{mA}$
Gate Threshold Voltage	$V_{GS(th)}$	2	3	4	V	$V_{DS} = V_{GS}, I_D=0.25\text{mA}$
Zero Gate Voltage Drain Current	$I_{DSS}$	-	-	1	$\mu\text{A}$	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$
Gate Leakage Current	$I_{GSS}$	-	-	100	nA	$V_{GS} = \pm 30\text{V}, V_{DS} = 0\text{V}$
Drain-Source On State Resistance	$R_{DS(ON)}$	-	0.104	0.115	$\Omega$	$V_{GS} = 10\text{V}, I_D = 14.5\text{A}$

**Reverse Diode Characteristics ( $T_c=25^{\circ}\text{C}$  unless otherwise specified)**

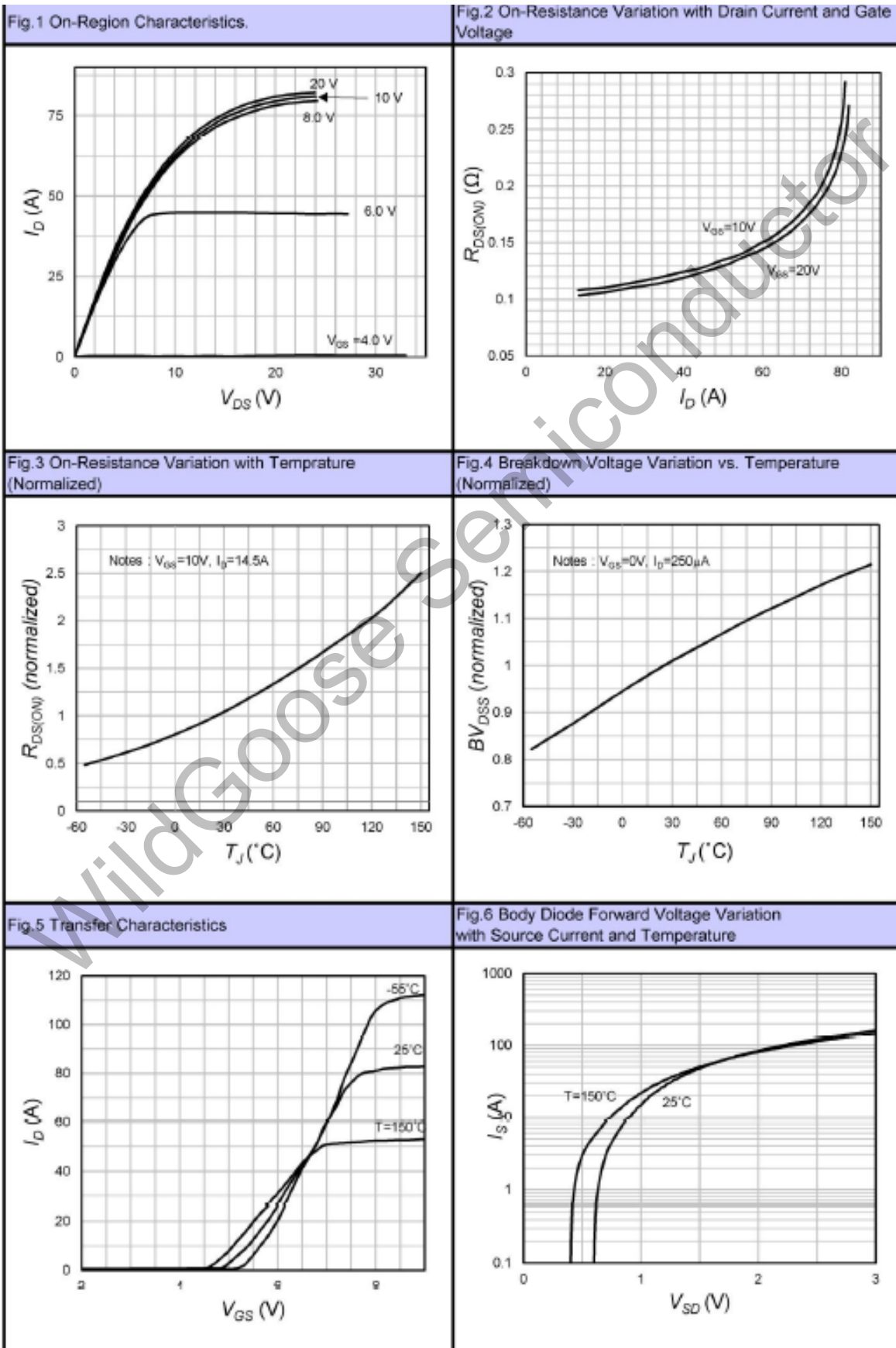
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Continuous Diode Forward Current	$I_{SD}$	-	-	33	A	
Diode Forward Voltage	$V_{SD}$	-	-	1.4	V	$I_{SD} = 33.0\text{A}, V_{GS} = 0\text{V}$
Reverse Recovery Time	$t_{rr}$	-	587	-	ns	$I_{SD} = 33.0\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ $V_{DD} = 100\text{V}$
Reverse Recovery Charge	$Q_{rr}$	-	10.8	-	$\mu\text{C}$	
Reverse Recovery Current	$I_{rrm}$	-	36.6	-	A	

**Dynamic Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise specified)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Input Capacitance	$C_{iss}$	-	2720	-	pF	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V},$ $f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	-	1770	-		
Reverse Transfer Capacitance	$C_{rss}$	-	88	-		
Effective Output Capacitance Energy Related <sup>(3)</sup>	$C_{o(er)}$	-	74	-		
Turn On Delay Time	$t_{d(on)}$	-	46	-	ns	$V_{GS} = 10\text{V}, R_G = 25\Omega,$ $V_{DS} = 300\text{V}, I_D = 33\text{A}$
Rise Time	$t_r$	-	114	-		
Turn Off Delay Time	$t_{d(off)}$	-	247	-		
Fall Time	$t_f$	-	92	-		
Total Gate Charge	$Q_g$	-	77	-	nC	$V_{GS} = 10\text{V}, V_{DS} = 480\text{V},$ $I_D = 33\text{A}$
Gate – Source Charge	$Q_{gs}$	-	17	-		
Gate – Drain Charge	$Q_{gd}$	-	33	-		
Gate Resistance	$R_G$	-	3.2	-	$\Omega$	$V_{GS} = 0\text{V}, f = 1.0\text{MHz}$

3)  $C_{o(er)}$  is a capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0V to 80%  $V_{(BR)DSS}$

■ Characteristic Graph





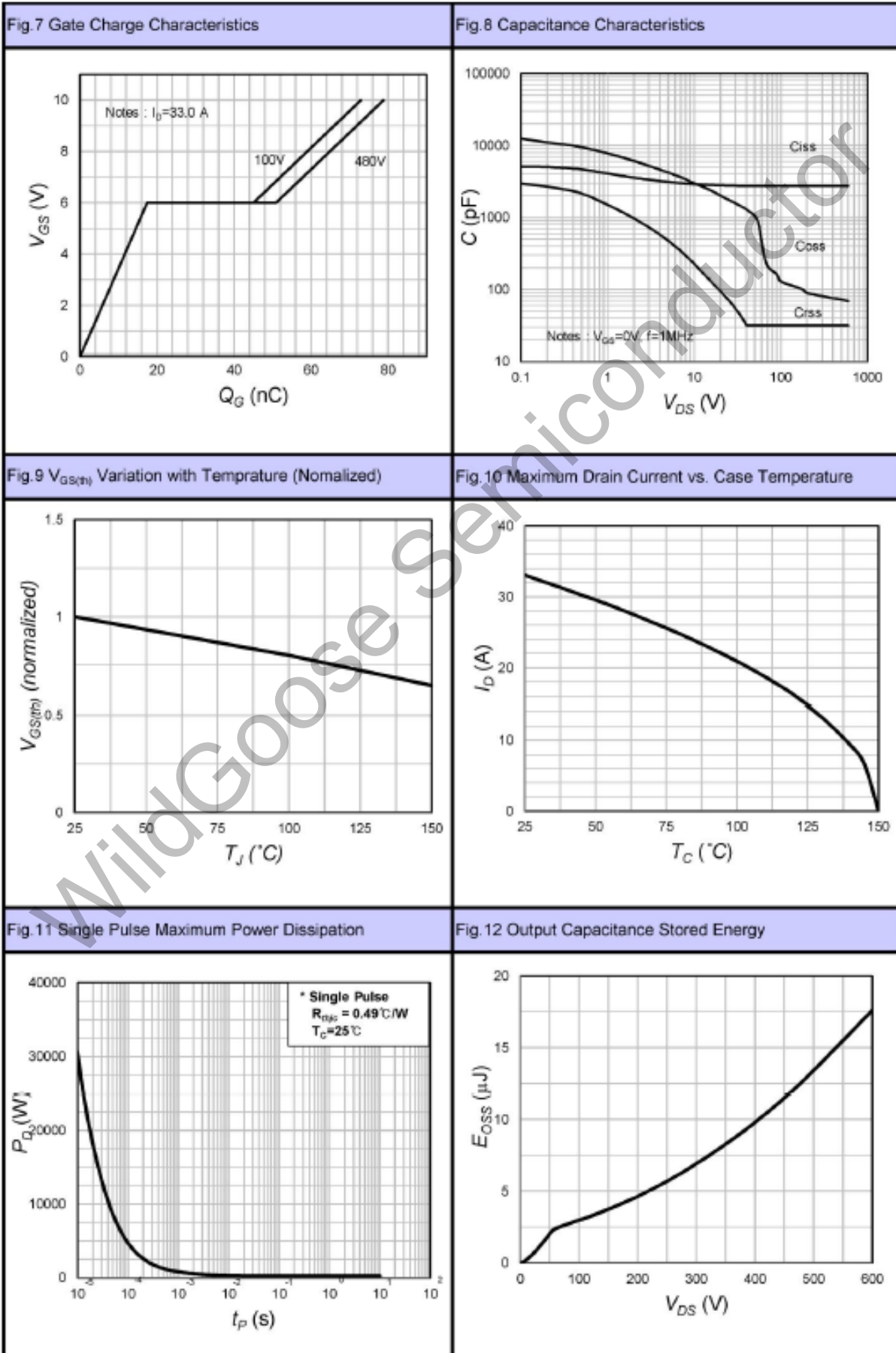


Fig.13 Transient Thermal Response Curve

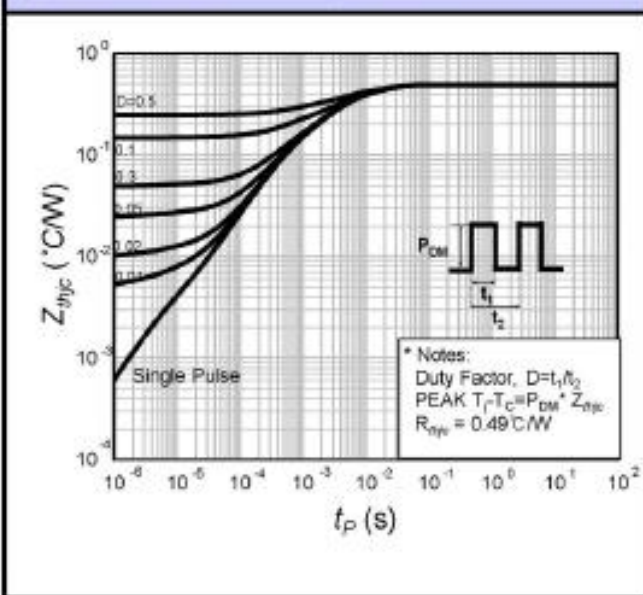
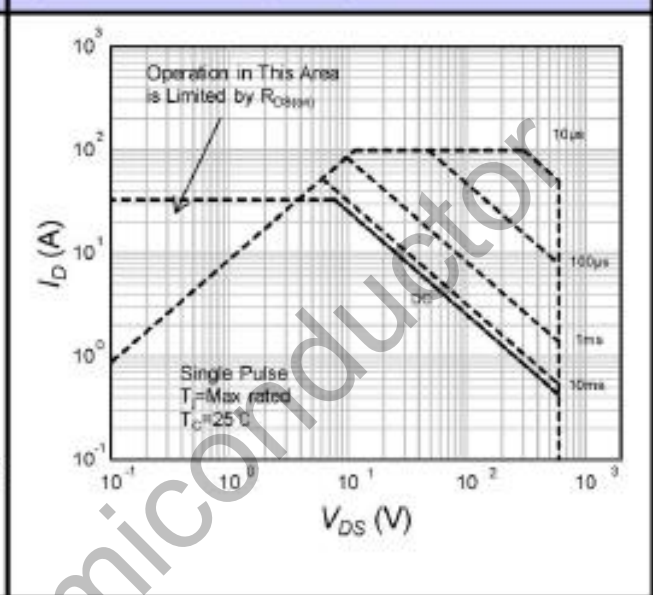


Fig.14 Maximum Safe Operating Area



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Test Circuit & Waveform

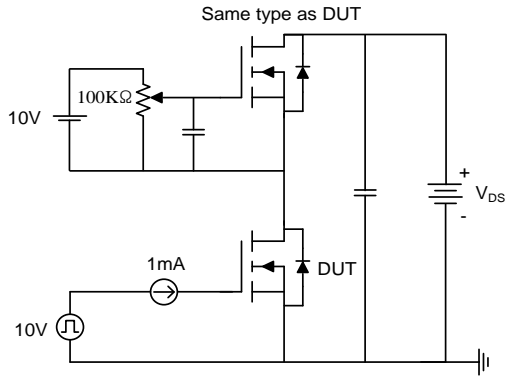


Fig15-1. Gate charge measurement circuit

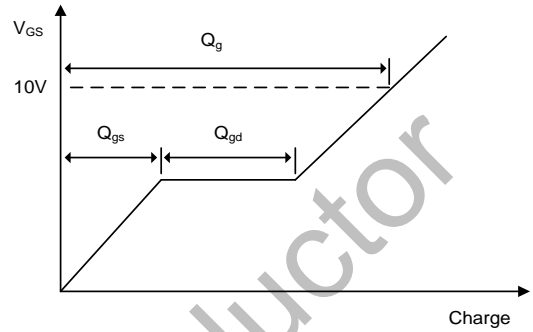


Fig15-2. Gate charge waveform

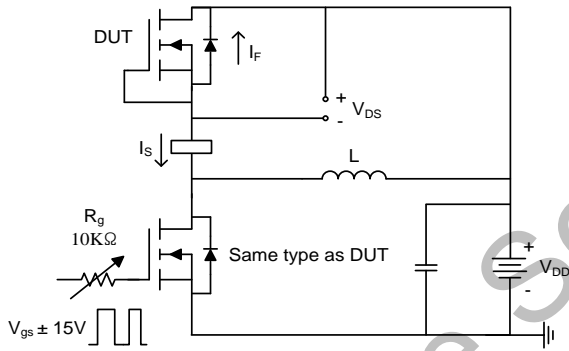


Fig16-1. Diode reverse recovery test circuit

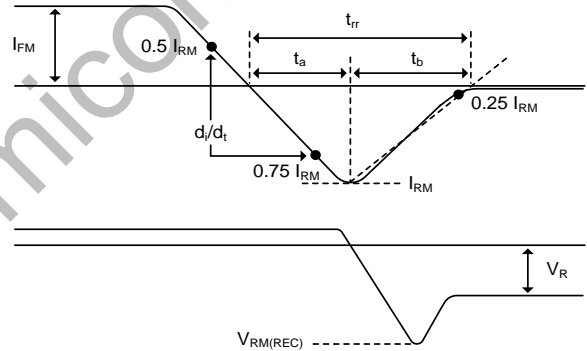


Fig16-1. Diode reverse recovery test waveform

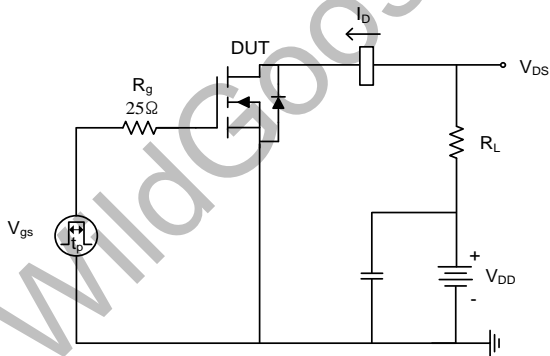


Fig17-1. Switching time test circuit for resistive load

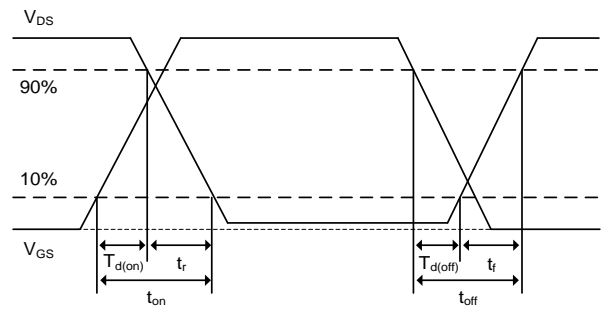


Fig17-2. Switching time waveform

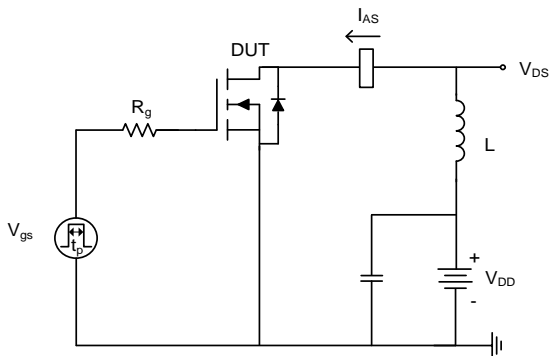


Fig18-1. Unclamped inductive load test circuit

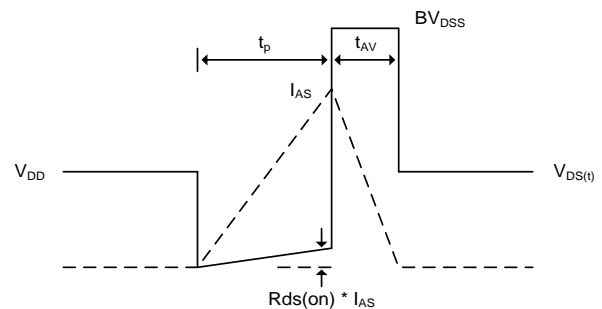
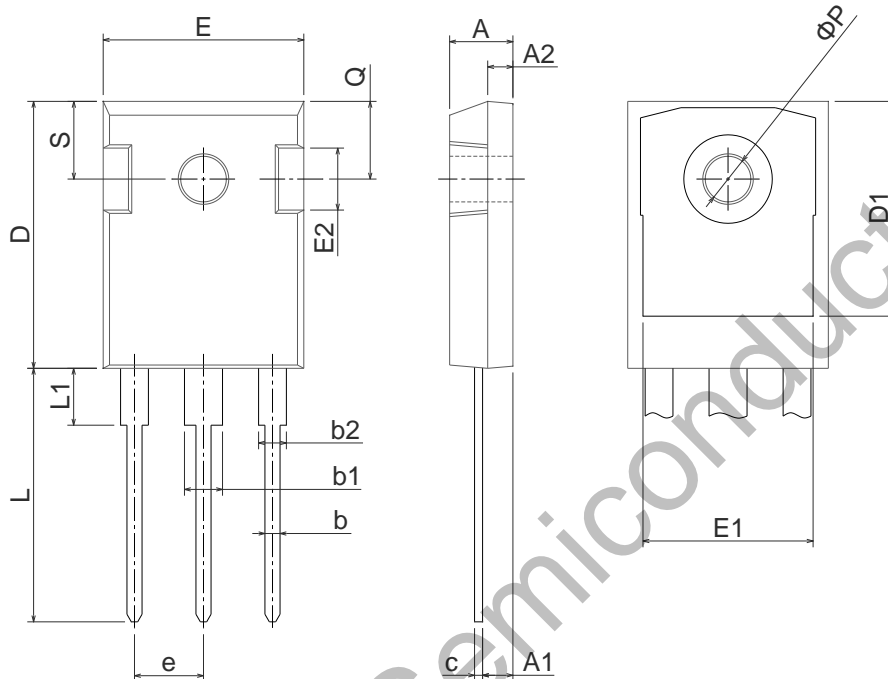


Fig18-2. Unclamped inductive waveform

**Package Dimension**

TO-247

Unit:mm



Dimension	Min(mm)	Max(mm)
A	4.70	5.31
A1	2.20	2.60
A2	1.50	2.49
b	0.99	1.40
b1	2.59	3.43
b2	1.65	2.39
c	0.38	0.89
D	20.30	21.46
D1	13.08	-
E	15.45	16.26
E1	13.06	14.02
E2	4.32	5.49
e	5.45BSC	
L	19.81	20.57
L1	-	4.50
ΦP	3.50	3.70
Q	5.38	6.20
S	6.15BSC	

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